

Product / Process Change Notice

Parts Affected:

CZDM8502N MOSFET manufactured in the SOT-223 case.

Extent of Change:

Change in assembly site; and change in die attach method from silver epoxy to soft solder.

Reason for Change:

As part of Central Semiconductor's supply chain risk mitigation initiative, and in an effort to ensure an undisrupted supply of product, a change in assembly site is being made for the referenced product. Device specifications, quality, and reliability are not impacted by this change.

Effect of Change:

This change does not affect the fit, form or function of the device.

Qualification:

Test	Condition	Duration	Failure rate
Temperature Cycling (T.C.)	TA= -55+0°C/-10°C 15min(Min) TA= +150+15°C/-0°C 15min(Min) Transfer time less than 1min. The load should reach temp. within 15min	1000 Cycles	0/77
Resistance to Solder Heat (R.S.H.)	T =260°C ±5°C Dwell time = 10 sec.	1 Cycle	0/5
Thermal Shock Test (T.S.T.)	TA=0°C (5 min) ~ +100°C (5 min)	100 Cycles	0/77

Effective Date of Change:

Existing inventory will be shipped until depleted.

Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.



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PCN #211
Notification Date:
March 19, 2021

As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	